

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10552441			
<b>Filing Date:</b>	07-Oct-2005			
<b>Title of Invention:</b>	EPOXY RESIN MOLDING MATERIAL FOR SEALING USE AND SEMICONDUCTOR DEVICE			
First Named Inventor/Applicant Name:	Ryoichi Ikezawa			
<b>Filer:</b>	William Ivan Solomon/Ricardo Perez			
<b>Attorney Docket Number:</b>	1204.45467X00			
Filed as Large Entity				
<b>U.S. National Stage under 35 USC 371 Filing Fees</b>				
<b>Description</b>	<b>Fee Code</b>	<b>Quantity</b>	<b>Amount</b>	<b>Sub-Total in USD(\$)</b>
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
Post-Allowance-and-Post-Issuance:				
Utility Appl issue fee	1501	1	1440	1440
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
Extension-of-Time:				
Miscellaneous:				
Printed copy of patent - no color	8001	4	3	12
Total in USD (\$)				1752